

Title (en)

DETERMINING A REMAINING INTENDED SERVICE LIFE OF A SEMICONDUCTOR MODULE

Title (de)

BESTIMMEN EINER NOCH VERBLEIBENDEN BESTIMMUNGSGEMÄSSEN NUTZBARKEIT EINES HALBLEITERMODULS

Title (fr)

DÉTERMINATION DE LA DURÉE DE SERVICE PRÉVUE RESTANTE D'UN MODULE À SEMI-CONDUCTEUR

Publication

**EP 3881418 B1 20221019 (DE)**

Application

**EP 19829101 A 20191217**

Priority

- EP 19154453 A 20190130
- EP 2019085666 W 20191217

Abstract (en)

[origin: WO2020156733A1] The invention relates to a method for determining the remaining usability of a semiconductor module (24) in normal use, which semiconductor module is thermally coupled to a cooling device (20), in which method a predefined electrical load (34) is applied to the semiconductor module (24) while predefined cooling is effected by the cooling device (20), a temperature (36) of a semiconductor element (28) of the semiconductor module (24) is sensed at least for the predefined electrical load (34) on the semiconductor module (24), the sensed temperature (36) is compared with a comparison temperature (40) in a first comparison, the comparison temperature (40) being assigned to the predefined electrical load (34) with the predefined cooling, and prediction data (44) for the remaining usability of the semiconductor module (24) in normal use up to a usability end are determined at least in accordance with the first comparison.

IPC 8 full level

**H02M 1/32** (2007.01); **G01R 31/26** (2020.01); **H01L 21/66** (2006.01); **H03K 17/08** (2006.01)

CPC (source: EP US)

**G01R 31/2619** (2013.01 - US); **G01R 31/2642** (2013.01 - US); **G01R 31/2817** (2013.01 - EP US); **G01R 31/42** (2013.01 - EP); **H02M 1/32** (2013.01 - EP); **H03K 17/08** (2013.01 - US); **H03K 17/18** (2013.01 - EP); **H02M 1/327** (2021.05 - EP); **H03K 2017/0806** (2013.01 - EP US)

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)

**EP 3691098 A1 20200805**; CN 113366747 A 20210907; EP 3881418 A1 20210922; EP 3881418 B1 20221019; US 11480607 B2 20221025; US 2022043050 A1 20220210; WO 2020156733 A1 20200806

DOCDB simple family (application)

**EP 19154453 A 20190130**; CN 201980090811 A 20191217; EP 19829101 A 20191217; EP 2019085666 W 20191217; US 201917426510 A 20191217